

№ 20220114-SPC-HIC
 Date: Jan 12th 2022

To: Valued Customers

Subject: Change in packing method of SP-Cap

We appreciate your continued support.

We will make change to the packaging method of ALL series of SP-Cap as below.

[Content of Change]

Current: Desiccant(silica gel) →After change: Desiccant(*) + HIC
 *Can meet MIL-D-3464

[Reason for change]

Customer request

◆Affected Part Numbers

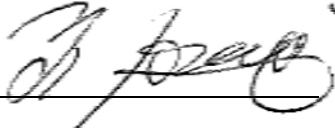
Conductive Polymer Capacitors SP-Cap All series

Part Number : Part number starting "EEF", "ECG" and "EEJ" are included.




◆Application start date : Jun 1st, 2022 (Production start date on running change)

We appreciate your understanding and cooperation.

Sincerely yours,


 Yoshinori Hourai
 General Manager
 Conductive Capacitor Business Unit
 Device Solutions Business Division
 Industry Solutions Company
 Panasonic Corporation

[Appendix]

Current (example)	After change (example)	
Desiccant(Silica gel)	Desiccant	HIC
		
	*Can meet MIL—D-3464	